# Gap Pad® HC 3.0

High-Compliance, Thermally Conductive, Low Modulus Material

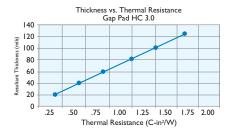
#### **Features and Benefits**

- Thermal Conductivity: 3.0 W/m-K
- High-compliance, low compression stress
- Fiberglass reinforced for shear and tear resistance



Gap Pad® HC 3.0 is a soft and compliant gap filling material with a thermal conductivity of 3.0 W/m-K. The material offers exceptional thermal performance at low pressures due to a unique 3.0 W/m-K filler package and low-modulus resin formulation. The enhanced material is ideal for applications requiring low stress on components and boards during assembly. Gap Pad® HC 3.0 maintains a conformable nature that allows for quick recovery and excellent wet-out characteristics, even to surfaces with high roughness and/or topography.

Gap Pad® HC 3.0 is offered with natural inherent tack on both sides of the material, eliminating the need for thermally-impeding adhesive layers. The top side has minimal tack for ease of handling. Gap Pad® HC 3.0 is supplied with protective liners on both sides.



TYPICAL PROPERTIES OF GAP PAD HC 3.0					
PROPERTY	IMPERIAL VALUE	METRIC VALUE		TEST METHOD	
Color	Blue	Blue		Visual	
Reinforcement Carrier	Fiberglass	Fiberglass		_	
Thickness (inch) / (mm)	0.020 to 0.125	0.508 to 3.175		ASTM D374	
Inherent Surface Tack	2	2		_	
Density (Bulk Rubber) (g/cc)	3.1	3.1		ASTM D792	
Heat Capacity (J/g-K)	1.0	1.0		ASTM E1269	
Hardness (Bulk Rubber) (Shore 00) (4)	15	15		ASTM D2240	
Young's Modulus (psi) / (kPa) (1)	16	110		ASTM D575	
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200		_	
ELECTRICAL					
Dielectric Breakdown Voltage (Vac) (3)	>5000	>5000		ASTM D149	
Dielectric Constant (1000 Hz)	6.5	6.5		ASTM D 150	
Volume Resistivity (Ohm-meter)	1010	1010		ASTM D257	
Flame Rating	V-O	V-O		U.L. 94	
THERMAL					
Thermal Conductivity (W/m-K) (2)	3.0	3.0		ASTM D5470	
THERMAL PERFORMANCE vs. STRAIN					
	Deflection (% strain)		10	20	30
Thermal Impedance (°C-in²/W) 0.040" (2)			0.57	0.49	0.44
D. V M. J					

- 1) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch² after 5 minutes of compression at 10% strain on a 1mm thickness material.
- 2) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.
- 3) Minimum value at 20 mil.
- 4) Thirty second delay value on Shore 00 hardness scale.

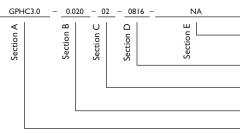
## **Typical Applications Include:**

- Telecommunications
- ASICs and DSPs
- Consumer electronics
- Thermal modules to heat sinks

## **Configurations Available:**

• Sheet form and die-cut parts

#### **Building a Part Number**



#### **Standard Options**

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

0816 = Standard sheet size 8" x 16", or 00 = custom configuration

02 = Natural tack, both sides (With Fiberglass)

Standard thicknesses available: 0.020", 0.040", 0.060", 0.080", 0.100", 0.125"

GPHC3.0 = Gap Pad HC 3.0 Material with fiberglass

Note: To build a part number, visit our website at www.bergquistcompany.com.



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